Unit in mm

TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

### **TLP504A,TLP504A-2**

## Programmable Controllers AC / DC-Input Module Solid State Relay

The TOSHIBA TLP504A and TLP504A-2 consists of a photo-transistor optically coupled to a gallium arsenide infrared emitting diode.

The TLP504A offers two isolated channels in an eight lead plastic DIP package, while the TLP504A-2 provides four isolated channels in a sixteen plastic DIP package.

• Collector-emitter voltage: 55 V (min.)

• Current transfer ratio: 50% (min.)
Rank GB: 100% (min.)

• Isolation voltage: 2500 Vrms (min.)

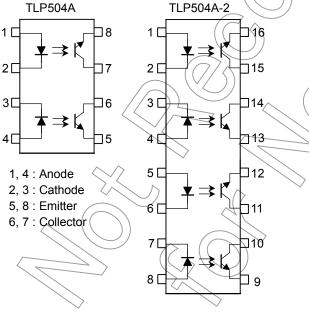
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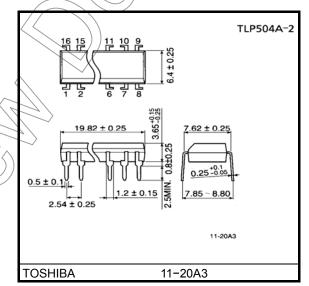
# TLP504A TLP504A TLP504A TLP504A TLP504A TLP504A TLP504A TOSHIBA TLP504A TLP504A

Weight: 0.54/g/(typ.)

#### Pin Configurations (top view)



1, 4, 5, 8 : Anode 2, 3, 6, 7 : Cathode 9, 12, 13, 16 : Emitter 10, 11, 14, 15 : Collector



Weight: 1.1 g (typ.)



#### Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Ra	Unit	
	Characteristic	Symbol	TLP504A	TLP504A-2	Offic
	Forward current	lF	60	50	mA
LED	Forward current derating	ΔI <sub>F</sub> / °C	–0.7 (Ta ≥ 39°C)	–0.5 (Ta ≥ 25°C)	mA /°C
	Pulse forward current	I <sub>FP</sub>	1 (100µs pu	Α	
	Reverse voltage	V <sub>R</sub>		V	
	Junction temperature	Tj	12	> °C	
	Collector-emitter voltage	V <sub>CEO</sub>	5	V	
	Emitter-collector voltage	V <sub>ECO</sub>	-	V	
'n	Collector current	IC	5	mA	
Detector	Collector power dissipation (1 circuit)	PC	150	mW	
	Collector power dissipation derating (1 circuit Ta ≥ 25°C)	ΔP <sub>C</sub> / °C	-1.5	-1.0	mW /°C
	Junction temperature	Tj		25	3
Storage temperature range		T <sub>stg</sub>	55*	1/50	(\$\sqrt{\phi}\)
Оре	erating temperature range	T <sub>opr</sub>	55-	~100	) V
Lead soldering temperature		T <sub>sol</sub>	260 (	°C	
Total package power dissipation		R <sub>T</sub>	250	150	mW
Total package power dissipation derating (Ta ≥ 25°C)		ΔP <sub>T</sub> / °C	-2.5	1.5	mW / °C
Isol	ation voltage	BVS	2500 (AC, 1mín., R.	H.≤ 60%) (Note 1)	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Device considered a two terminal device: LED side pins shorted together and detector side pins shorted together.

#### **Recommended Operating Conditions**

Characteristics	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Vcc	_	5	24	V
Forward current	l <sub>F</sub>	_	16	20	mA
Collector current	IC	_	1	10	mA
Operating temperature	T <sub>opr</sub>	-25	_	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

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#### Individual Electrical Characteristics (Ta = 25°C)

	Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
LED	Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA	1.0	1.15	1.3	V
	Reverse current	I <sub>R</sub>	V <sub>R</sub> = 5 V	_	_	10	μΑ
	Capacitance	C <sub>T</sub>	V = 0, f = 1 MHz	\ <u></u>	30	-	pF
	Collector–emitter breakdown voltage	V <sub>(BR)</sub> CEO	I <sub>C</sub> = 0.5 mA	55	7/	1	V
Detector	Emitter-collector breakdown voltage	V <sub>(BR)</sub> ECO	I <sub>E</sub> = 0.1 mA		)	ı	V
	Collector dark current	lana	V <sub>CE</sub> = 24 V	$\mathcal{I}$	10	100	nA
	Collector dark current	ICEO	V <sub>CE</sub> = 24 V, Ta = 85°C	_	2	50	μΑ
	Capacitance collector to emitter	C <sub>CE</sub>	V = 0, f = 1 MHz	_	10		pF

#### Coupled Electrical Characteristics (Ta = 25°C)

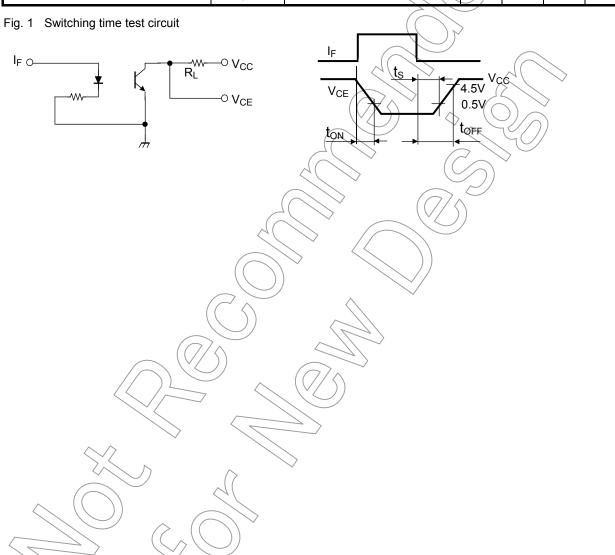
Characteristic	Symbol	Test Condition	Min.	Typ	) Max.	Unit
Current transfer ratio	I <sub>C</sub> / I <sub>F</sub>	I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 5 V Rank GB	50		600 600	%
Saturated CTR	I <sub>C</sub> / I <sub>F</sub> (sat)	IE = 1 mA, V <sub>CE</sub> = 0.4 V Rank GB	30	60 —	_	%
	4(	IC = 2,4 mA, I <sub>F</sub> ≠ 8 mA	_	_	0.4	
Collector–emitter saturation voltage	V <sub>CE</sub> (sat)	1 <sub>C</sub> = 0.2 mA, I <sub>F</sub> = 1 mA Rank GB	-	0.2	_	V
<u> </u>		Rank GB	_	_	0.4	

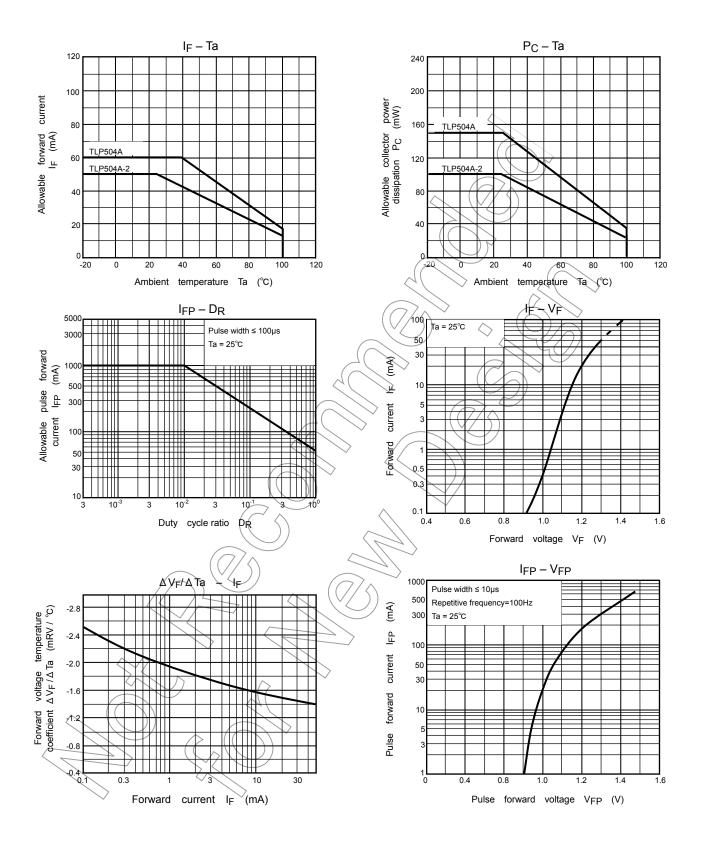
#### Isolation Characteristics (Ta = 25°C)

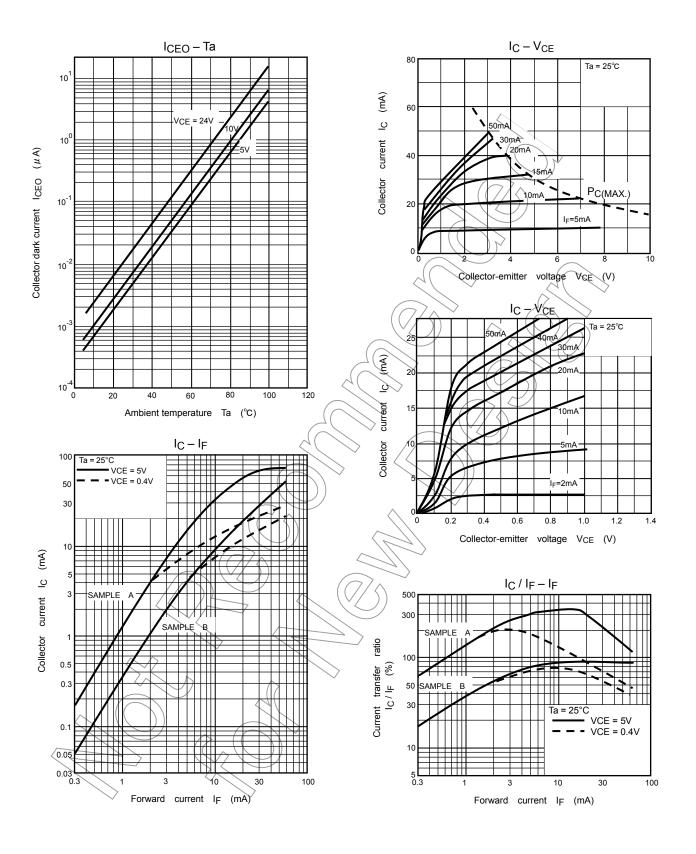
	$\wedge$					
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Capacitance input to output	Cs	V <sub>S</sub> = 0, f = 1 MHz	_	0.8	_	pF
Isolation resistance	Rs	V <sub>S</sub> = 500 V	5×10 <sup>10</sup>	10 <sup>14</sup>	_	Ω
$\rightarrow$		AC, 1 minute	2500	_	_	Vrms
Isolation voltage	BVS	AC, 1 second, in oil	_	5000	_	VIIIIS
	^	DC, 1 minute, in oil	_	5000	_	Vdc

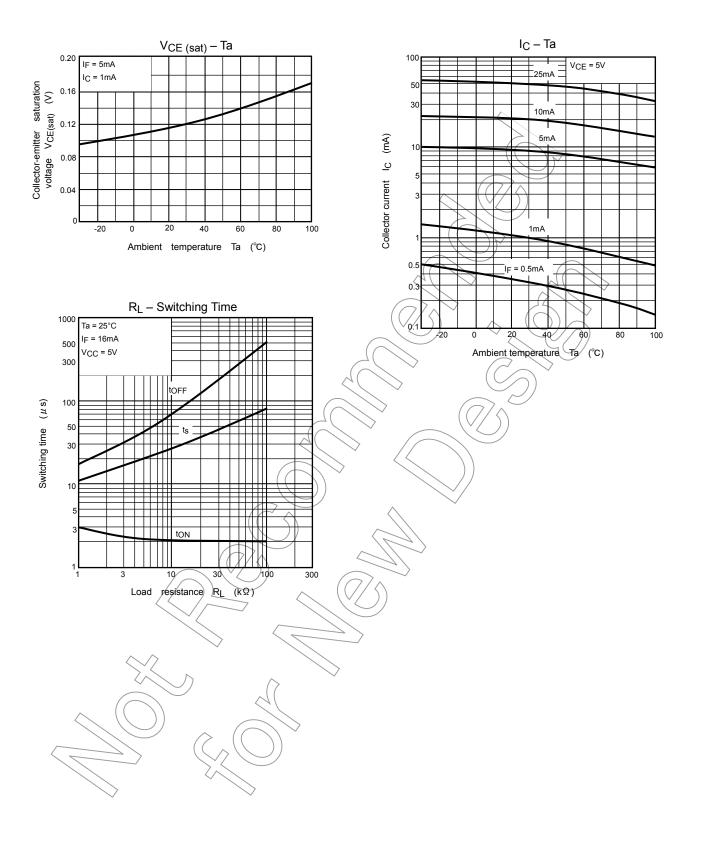
#### **Switching Characteristics (Ta = 25°C)**

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Rise time	t <sub>r</sub>		_	2	_	
Fall time	t <sub>f</sub>	V <sub>CC</sub> = 10 V, I <sub>C</sub> = 2 mA	_	3	_	ше
Turn-on time	t <sub>on</sub>	$R_L = 100\Omega$	_	3	_	μs
Turn-off time	t <sub>off</sub>			3	_	
Turn-on time	t <sub>ON</sub>		(F	) >2	_	
Storage time	ts	$R_L = 1.9 \text{ k}\Omega$ (Fig.1) $V_{CC} = 5 \text{ V, I}_F = 16 \text{ mA}$	$\nearrow$	15	_	μs
Turn-off time	toff			25	_	









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